


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VN5770AKPTR-E	APLR*VH57AEX	A	MUA1	2013-09-04
Amount	UoM	Unit type	ST ECOPACK Grade	
809.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	17.9x10.4x2.4	28	flat	
Comment				

Material Composition Declaration						Mfr Item Name	APLR*VH57AEX						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
die (s)	Other inorganic materials	3.056	mg	supplier	die	Silicon (Si)	7440-21-3		2.989	mg	978076	3695	
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.021	mg	6872	26	
die (s)				supplier	passivation	Indium Tin oxide (In2O3·SnO2)	50926-11-9		0.021	mg	6872	26	
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	327	1	
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	1309	5	
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.02	mg	6545	25	
Leadframe	Copper & its alloys	352.86	mg	supplier	alloy	Copper (Cu)	7440-50-8		343.585	mg	973715	424703	
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		8.081	mg	22901	9989	
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.487	mg	1380	602	
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.423	mg	1199	523	
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.284	mg	805	351	
Die attach		2.71	mg	JIG R	glue or tape	Lead (Pb)	7439-92-1	7a-Lead in high me	2.642	mg	974908	3266	
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		0.041	mg	15129	51	
Die attach				supplier	glue or tape	Tin (Sn)	7440-31-5		0.027	mg	9963	33	
Bonding wire		2.344		supplier	wire	Gold (Au)	7440-57-5		2.344	mg	1000000	2897	
encapsulation		445.522	mg	supplier	mold compound	Silica, vitreous	60676-86-0		356.417	mg	799999	440565	
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		31.187	mg	70001	38550	
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		17.821	mg	40000	22028	
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		26.731	mg	59999	33042	
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		5.346	mg	11999	6608	
encapsulation				JIG I	mold compound	Brominated Epoxy Resin	40039-93-8		6.683	mg	15000	8261	
encapsulation				supplier	mold compound	Carbon black	1333-86-4		1.337	mg	3001	1653	
connections coating	Solder	2.508	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.508	mg	1000000	3100	